




Drawing No.	*Rev.	Date	Page
BF5A04GA-NPD	C	2022/05/09	1/3

# APPROVAL SHEET

Part No:

BF5A04GA-NPD

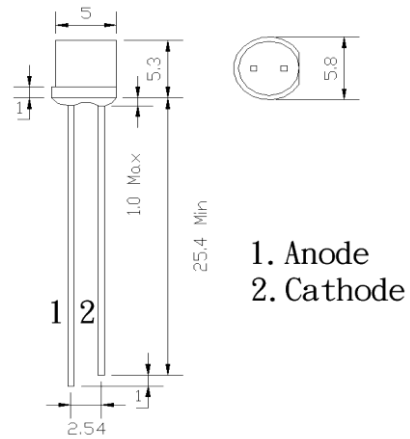
NOTE : Green Part

MAKER			CUSTOMER	
				
R&D	QA	Sales	Checked	Approved
				

Prepared	Checked	Approved
Rachel Lee	Sky Lin	Kenneth Wu

**DESCRIPTION:**

Device Type : BF5A04GA-NPD  
 Dice Material : Silicon  
 Lens Color : Water Clear  
 Lens Dimension : 5 mm



All epoxy resin dimension are in millimeter tolerance is  $\pm 0.2\text{mm}$

**Absolute Maximum Ratings at Ta=25°C**

Parameter	Symbol	Rating.	Unit
Power Dissipation	PC	100	mW
Operating Temperature	Topr	-40 ~ +85	°C
Storage Temperature	Tstr	-40 ~ +100	°C
Solder DIP (MAX. 5 seconds, 1.6mm from body) Temperature 260°C			

**Electrical and Optical Characteristics at Ta=25°C**

Description	Symbol	Condition	Min.	Typ.	Max.	Unit
Range of Spectral Bandwidth	Wp	-	400	-	670	nm
Peak Sensitivity Wavelength	Wp	-	-	630	-	nm
Reverse Light Current	IL	VR=5V.Ee=1mW/ cm <sup>2</sup>	-	10	-	uA
Reverse Dark Current	ID	VR =10V.Ee=0mW/ cm <sup>2</sup>	-	2	10	nA
Reverse breakdown voltage	VBR	IR=100uA.Ee=0mW/ cm <sup>2</sup>	35	-	-	V
Open-Circuit Voltage	Voc	Ee=5mW/cm <sup>2</sup> λp=940nm	-	0.35	-	V
Short- Circuit Current	Isc	Ee=1mW/cm <sup>2</sup> λp=940nm	-	40	-	μA
Rise Time/ Fall Time	tr/ tf	VR=10V RL=1KΩ	-	45 / 45	-	ns
Total Capacitance	Ct	VR =5V Ee=0mW/cm <sup>2</sup> f=1MHz	-	25	-	pF

Note: 1.The lead should be formed up to 5mm from the body of device without forming stress.  
 2. Soldering shall be performed after lead forming.  
 3. All dimensions are in millimeters

## LED LAMP Technical Data

### Typical Optical-Electrical Characteristic Curves

Collector Power Dissipation vs Ambient Temperature

